

What is claimed is:

1. A wafer dicing method comprising:
providing a wafer including a plurality of dies and a metal layer, layer, wherein each of the dies includes a surface and there is a scribe line formed between adjacent dies, and wherein the metal layer is formed on the scribe line;
placing the wafer on a bearing surface of a carrier; and
performing a cutting procedure and a contacting procedure simultaneously, wherein a cutter is used to cut the metal layer along the scribe line during the cutting procedure to form a plurality of cutting slots on the wafer such that a plurality of metal burrs remain on the cutting slots of the dies, and using a contacting portion of a brush to contact with each of the metal burrs along the cutting slot during the contacting procedure to prevent each of the metal burrs from protruding from the surface of each of the dies wherein, during the simultaneous cutting and contacting procedures, the contacting portion of the brush is arranged behind the cutter along a cutting direction of the cutter and the cutter and the contacting portion are located on the same scribe line and wherein, before performing the simultaneous cutting and contacting procedures, a first height exists between a terminal of the cutter and the bearing surface of the carrier and a second height exists between a contacting portion of the brush and the bearing surface of the carrier and wherein the first height is equal to or higher than the second height.
2. The wafer dicing method in accordance with claim 1, wherein each of the metal burrs is separated from the die or bent downwardly

toward the cutting slot when the contacting portion of the brush contacts with each of the metal burrs.

3. The wafer dicing method in accordance with claim 1, wherein the contacting portion of the brush is made of flexible material, and deformation of the contacting portion occurs during the contacting procedure.